

In the Claims

Applicant has submitted a complete new claim set showing marked up claims with insertions indicated by underlining.

Amend claims 14 and 15 as follows:

Claims 1-13 (cancelled)

14. (currently amended) An information signal isolator comprising:
 - a first substrate;
 - a first passive component formed on the first substrate;
 - an isolation layer formed over the first passive component;
 - a second passive component formed over the isolation layer;
 - the first and second passive components being coils;
 - an input for receiving an input signal; and
 - a driver circuit coupled between the input and one of said passive components.
15. (currently amended) An information isolator comprising:
 - a first substrate;
 - a first passive component formed on the first substrate;
 - an isolation layer formed over the first passive component;
 - a second passive component formed over the isolation layer;
 - the first and second passive components being capacitor plates;
 - an input for receiving an input signal; and
 - a driver circuit coupled between the input and one of said passive components.
16. (previously presented) The isolator of claim 14 or claim 15 wherein the first substrate is a semiconductor substrate.

17. (previously presented) The isolator of claim 16, wherein the driver circuit also is formed on the first semiconductor substrate.
18. (previously presented) The isolator of claim 16, further comprising a second substrate, wherein the driver circuit is formed on the second substrate.
19. (previously presented) The isolator of claim 14 or claim 15 wherein the first passive component is formed on top of the first substrate.
20. (previously presented) The isolator of claim 14 or claim 15 wherein the first passive component is formed into the first substrate.
21. (previously presented) The isolator of claim 14 or claim 15, further comprising a third passive component on the substrate, a second isolation layer over the third passive component, and a fourth passive component formed over the second isolation layer, wherein the driver circuit provides signals to the first and third passive components.
22. (previously presented) The isolator of claim 14 or claim 15, further comprising a third passive component on the substrate, a second isolation layer over the third passive component, and a fourth passive component formed over the second isolation layer, wherein the driver circuit provides signals to the second and fourth passive components.
23. (previously presented) The isolator of claim 22 wherein the first and second isolation layers are a single layer.
24. (previously presented) The isolator of claim 14 wherein the first and second passive components are referenced to separate, galvanically isolated grounds, and further including a Faraday shield between the first and second passive components,

with the Faraday shield referenced to the same ground as the second passive components.

25. (previously presented) The isolator of claim 21, wherein the third and fourth passive components are capacitor plates.

26. (previously presented) The isolator of claim 21, wherein the first, second, third, and fourth passive components are coils.

27. (previously presented) The isolator of claim 26 wherein the first and second passive components are referenced to separate, galvanically isolated grounds, and further including a Faraday shield between the first and second passive components, with the Faraday shield referenced to the same ground as the second passive components.